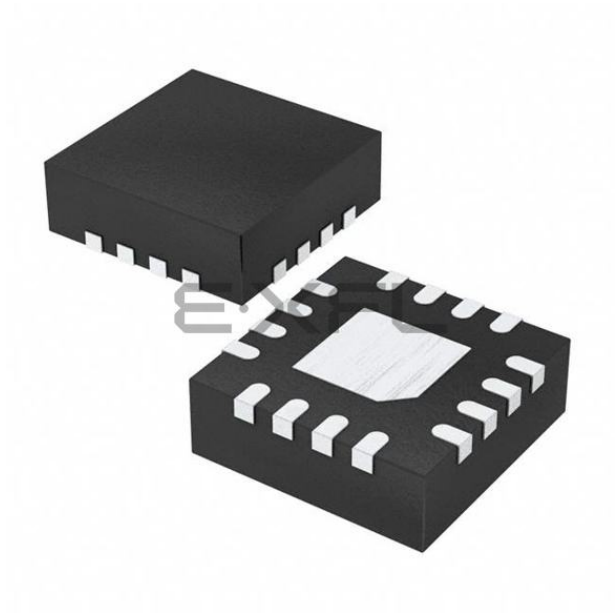

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	11
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-VQFN Exposed Pad
Supplier Device Package	16-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16hv610t-i-ml

2.0 MEMORY ORGANIZATION

2.1 Program Memory Organization

The PIC16F610/616/16HV610/616 has a 13-bit program counter capable of addressing an 8K x 14 program memory space. Only the first 1K x 14 (0000h-3FF) for the PIC16F610/16HV610 and the first 2K x 14 (0000h-07FFh) for the PIC16F616/16HV616 is physically implemented. Accessing a location above these boundaries will cause a wraparound within the first 1K x 14 space (PIC16F610/16HV610) and 2K x 14 space (PIC16F616/16HV616). The Reset vector is at 0000h and the interrupt vector is at 0004h (see Figure 2-1).

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC16F610/16HV610

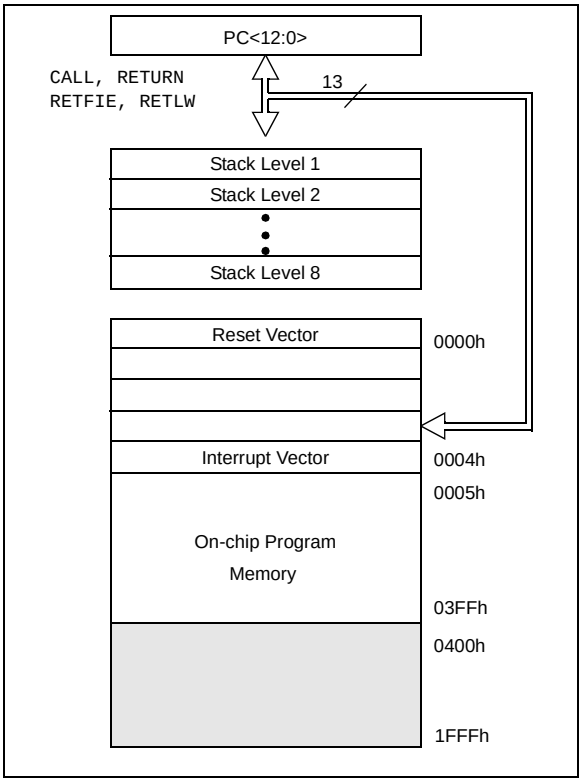
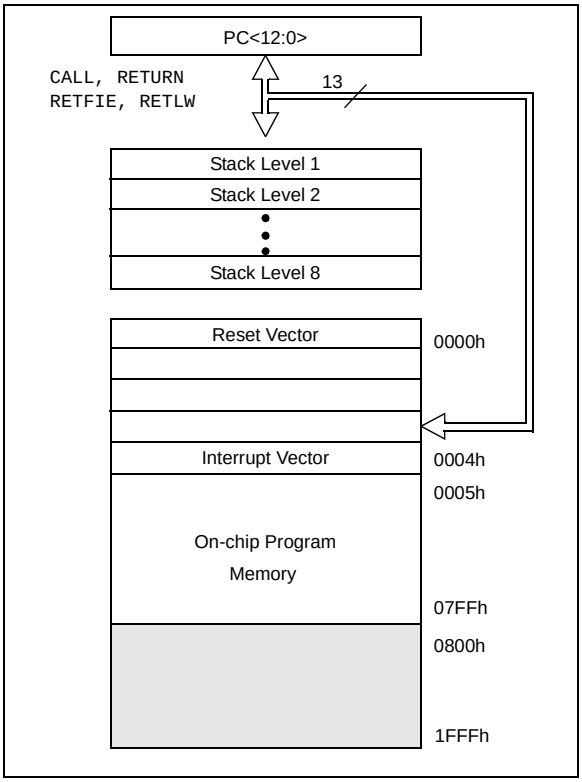


FIGURE 2-2: PROGRAM MEMORY MAP AND STACK FOR THE PIC16F616/16HV616



2.2 Data Memory Organization

The data memory (see Figure 2-4) is partitioned into two banks, which contain the General Purpose Registers (GPR) and the Special Function Registers (SFR). The Special Function Registers are located in the first 32 locations of each bank. PIC16F610/16HV610 Register locations 40h-7Fh in Bank 0 are General Purpose Registers, implemented as static RAM. PIC16F616/16HV616 Register locations 20h-7Fh in Bank 0 and A0h-BFh in Bank 1 are General Purpose Registers, implemented as static RAM. Register locations F0h-FFh in Bank 1 point to addresses 70h-7Fh in Bank 0. All other RAM is unimplemented and returns '0' when read. The RP0 bit of the STATUS register is the bank select bit.

RP0

0 → Bank 0 is selected

1 → Bank 1 is selected

Note:	The IRP and RP1 bits of the STATUS register are reserved and should always be maintained as '0's.

2.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 64 x 8 in the PIC16F610/16HV610 and 128 x 8 in the PIC16F616/16HV616. Each register is accessed, either directly or indirectly, through the File Select Register (FSR) (see **Section 2.4 "Indirect Addressing, INDF and FSR Registers"**).

2.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and peripheral functions for controlling the desired operation of the device (see Table 2-1). These registers are static RAM.

The special registers can be classified into two sets: core and peripheral. The Special Function Registers associated with the "core" are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

3.2 Clock Source Modes

Clock Source modes can be classified as external or internal.

- External Clock modes rely on external circuitry for the clock source. Examples are: Oscillator modules (EC mode), quartz crystal resonators or ceramic resonators (LP, XT and HS modes) and Resistor-Capacitor (RC) mode circuits.
- Internal clock sources are contained internally within the Oscillator module. The Oscillator module has two selectable clock frequencies: 4 MHz and 8 MHz

The system clock can be selected between external or internal clock sources via the FOSC<2:0> bits of the Configuration Word register.

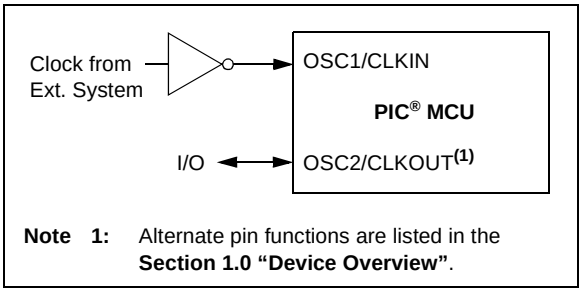
3.3 External Clock Modes

3.3.1 EC MODE

The External Clock (EC) mode allows an externally generated logic level as the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input and the OSC2 is available for general purpose I/O. Figure 3-2 shows the pin connections for EC mode.

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 3-2: EXTERNAL CLOCK (EC) MODE OPERATION



Note 1: Alternate pin functions are listed in the **Section 1.0 "Device Overview"**.

3.3.2 OSCILLATOR START-UP TIMER (OST)

If the Oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR) and when the Power-up Timer (PWRT) has expired (if configured), or a wake-up from Sleep. During this time, the program counter does not increment and program execution is suspended. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the Oscillator module. When switching between clock sources, a delay is required to allow the new clock to stabilize. These oscillator delays are shown in Table 3-1.

TABLE 3-1: OSCILLATOR DELAY EXAMPLES

Switch From	Switch To	Frequency	Oscillator Delay
Sleep/POR	INTOSC	4 MHz to 8 MHz	Oscillator Warm-Up Delay (TWARM)
Sleep/POR	EC, RC	DC – 20 MHz	2 Instruction Cycles
Sleep/POR	LP, XT, HS	32 kHz to 20 MHz	1024 Clock Cycles (OST)

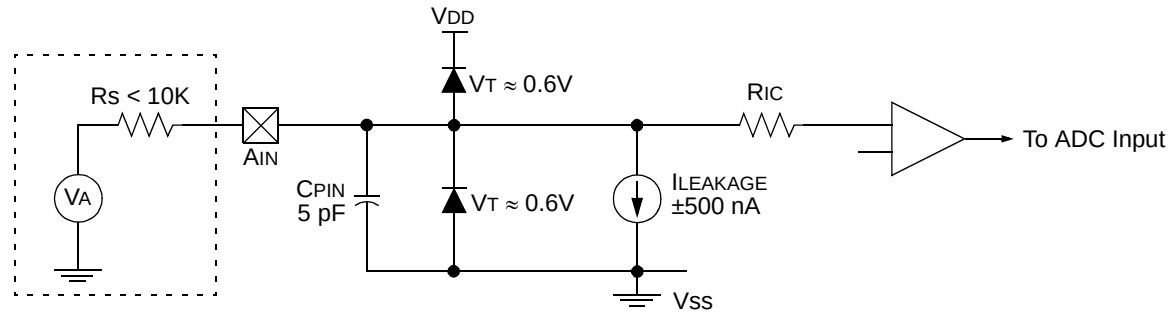
8.7 Comparator Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 8-6. Since the analog input pins share their connection with a digital input, they have reverse biased ESD protection diodes to VDD and VSS. The analog input, therefore, must be between VSS and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur.

A maximum source impedance of 10 kΩ is recommended for the analog sources. Also, any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current to minimize inaccuracies introduced.

Note 1:	When reading a PORT register, all pins configured as analog inputs will read as a '0'. Pins configured as digital inputs will convert as an analog input, according to the input specification.
2:	Analog levels on any pin defined as a digital input, may cause the input buffer to consume more current than is specified.

FIGURE 8-6: ANALOG INPUT MODEL



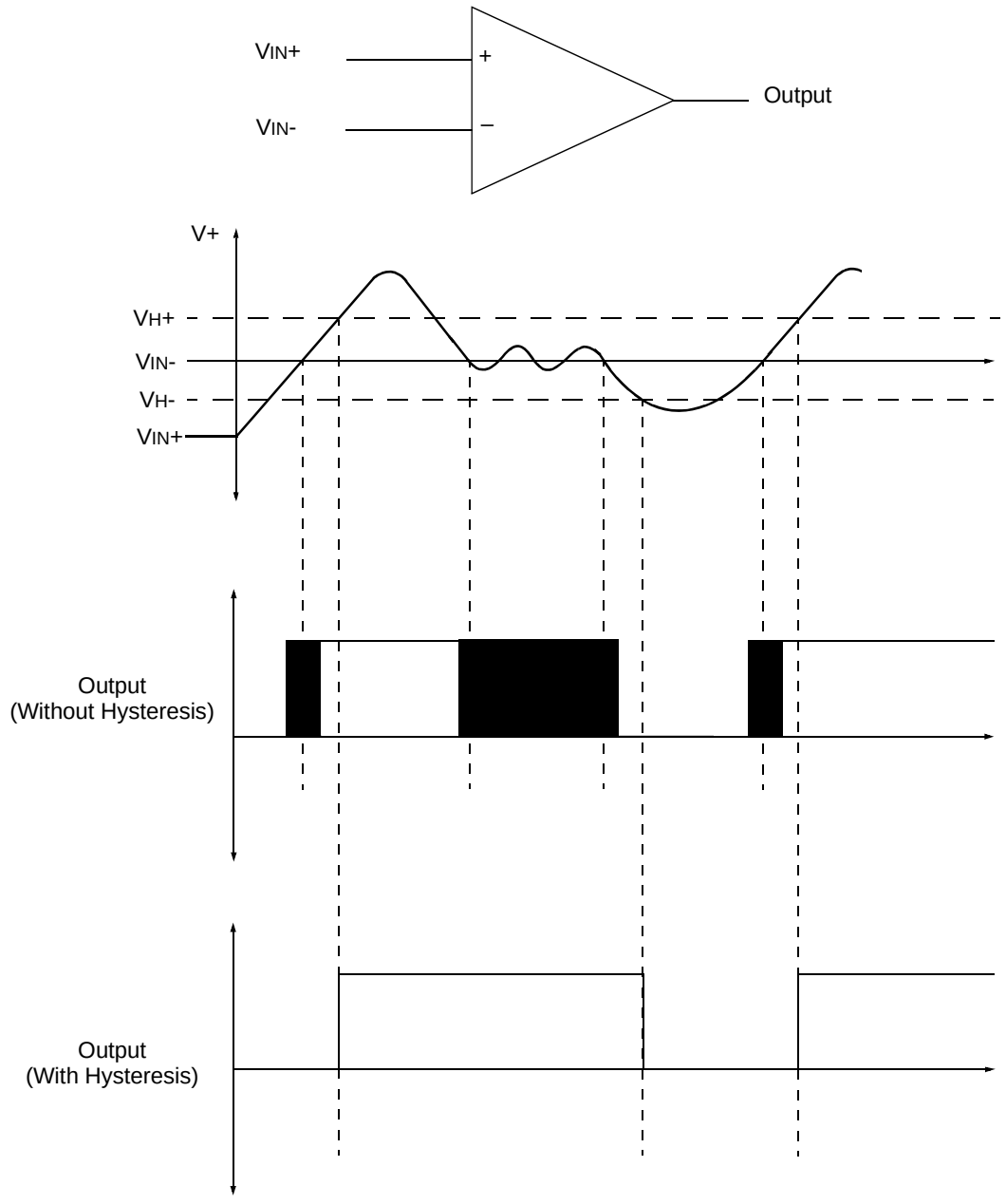
Legend: CPIN = Input Capacitance
ILEAKAGE = Leakage Current at the pin due to various junctions
RIC = Interconnect Resistance
RS = Source Impedance
VA = Analog Voltage
VT = Threshold Voltage

8.9 Comparator Hysteresis

Each comparator has built-in hysteresis that is user enabled by setting the C1HYS or C2HYS bits of the CM2CON1 register. The hysteresis feature can help filter noise and reduce multiple comparator output transitions when the output is changing state.

Figure 8-9 shows the relationship between the analog input levels and digital output of a comparator with and without hysteresis. The output of the comparator changes from a low state to a high state only when the analog voltage at V_{IN+} rises above the upper hysteresis threshold (V_{H+}). The output of the comparator changes from a high state to a low state only when the analog voltage at V_{IN+} falls below the lower hysteresis threshold (V_{H-}).

FIGURE 8-7: COMPARATOR HYSTERESIS



Note: The black areas of the comparator output represents the uncertainty due to input offsets and response time.

REGISTER 8-4: SRCON0: SR LATCH CONTROL 0 REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/S-0	R/S-0	U-0	R/W-0
SR1(2)	SR0(2)	C1SEN	C2REN	PULSS	PULSR	—	SRCLKEN
bit 7							bit 0

Legend:		S = Bit is set only -	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **SR1:** SR Latch Configuration bit(2)
- 1 = C2OUT pin is the latch $\overline{Q}$ output
- 0 = C2OUT pin is the C2 comparator output

bit 6 **SR0:** SR Latch Configuration bits(2)
- 1 = C1OUT pin is the latch Q output
- 0 = C1OUT pin is the C1 Comparator output

bit 5 **C1SEN:** C1 Set Enable bit
- 1 = C1 comparator output sets SR latch
- 0 = C1 comparator output has no effect on SR latch

bit 4 **C2REN:** C2 Reset Enable bit
- 1 = C2 comparator output resets SR latch
- 0 = C2 comparator output has no effect on SR latch

bit 3 **PULSS:** Pulse the SET Input of the SR Latch bit
- 1 = Triggers pulse generator to set SR latch. Bit is immediately reset by hardware.
- 0 = Does not trigger pulse generator

bit 2 **PULSR:** Pulse the Reset Input of the SR Latch bit
- 1 = Triggers pulse generator to reset SR latch. Bit is immediately reset by hardware.
- 0 = Does not trigger pulse generator

bit 1 **Unimplemented:** Read as '0'

bit 0 **SRCLKEN:** SR Latch Set Clock Enable bit
- 1 = Set input of SR latch is pulsed with SRCLK
- 0 = Set input of SR latch is not pulsed with the SRCLK

Note 1: The C1OUT and C2OUT bits in the CMxCON0 register will always reflect the actual comparator output (not the level on the pin), regardless of the SR latch operation.

2: To enable an SR Latch output to the pin, the appropriate CxOE, and TRIS bits must be properly configured.

REGISTER 8-5: SRCON1: SR LATCH CONTROL 1 REGISTER

R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
SRCS1	SRCS0	—	—	—	—	—	—
bit 7							bit 0

Legend:		S = Bit is set only -	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **SRCS<1:0>:** SR Latch Clock Prescale bits
- 00 = Fosc/16
- 01 = Fosc/32
- 10 = Fosc/64
- 11 = Fosc/128

bit 5-0 **Unimplemented:** Read as '0'

9.2.7 ADC REGISTER DEFINITIONS

The following registers are used to control the operation of the ADC.

REGISTER 9-1: ADCON0: A/D CONTROL REGISTER 0

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	VCFG	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **ADFM:** A/D Conversion Result Format Select bit
1 = Right justified
0 = Left justified

bit 6 **VCFG:** Voltage Reference bit
1 = V_{REF} pin
0 = V_{DD}

bit 5-2 **CHS<3:0>:** Analog Channel Select bits
0000 = Channel 00 (AN0)
0001 = Channel 01 (AN1)
0010 = Channel 02 (AN2)
0011 = Channel 03 (AN3)
0100 = Channel 04 (AN4)
0101 = Channel 05 (AN5)
0110 = Channel 06 (AN6)
0111 = Channel 07 (AN7)
1000 = Reserved – do not use
1001 = Reserved – do not use
1010 = Reserved – do not use
1011 = Reserved – do not use
1100 = CV_{REF}
1101 = 0.6V Fixed Voltage Reference(1)
1110 = 1.2V Fixed Voltage Reference(1)
1111 = Reserved – do not use

bit 1 **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit
1 = A/D conversion cycle in progress. Setting this bit starts an A/D conversion cycle.
This bit is automatically cleared by hardware when the A/D conversion has completed.
0 = A/D conversion completed/not in progress

bit 0 **ADON:** ADC Enable bit
1 = ADC is enabled
0 = ADC is disabled and consumes no operating current

Note 1: When the CHS<3:0> bits change to select the 1.2V or 0.6V Fixed Voltage Reference, the reference output voltage will have a transient. If the Comparator module uses this VP6 reference voltage, the comparator output may momentarily change state due to the transient.

10.0 ENHANCED CAPTURE/ COMPARE/PWM (WITH AUTO-SHUTDOWN AND DEAD BAND) MODULE (PIC16F616/16HV616 ONLY)

The Enhanced Capture/Compare/PWM module is a peripheral which allows the user to time and control different events. In Capture mode, the peripheral allows the timing of the duration of an event. The Compare mode allows the user to trigger an external event when a predetermined amount of time has expired. The PWM mode can generate a Pulse-Width Modulated signal of varying frequency and duty cycle.

Table 10-1 shows the timer resources required by the ECCP module.

TABLE 10-1: ECCP MODE – TIMER RESOURCES REQUIRED

ECCP Mode	Timer Resource
Capture	Timer1
Compare	Timer1
PWM	Timer2

REGISTER 10-1: CCP1CON: ENHANCED CCP1 CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
P1M1	P1M0	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-6 **P1M<1:0>:** PWM Output Configuration bits
If CCP1M<3:2> = 00,01,10:
xx = P1A assigned as Capture/Compare input; P1B, P1C, P1D assigned as port pins
If CCP1M<3:2> = 11:
00 = Single output; P1A modulated; P1B, P1C, P1D assigned as port pins
01 = Full-Bridge output forward; P1D modulated; P1A active; P1B, P1C inactive
10 = Half-Bridge output; P1A, P1B modulated with dead-time control; P1C, P1D assigned as port pins
11 = Full-Bridge output reverse; P1B modulated; P1C active; P1A, P1D inactive

bit 5-4 **DC1B<1:0>:** PWM Duty Cycle Least Significant bits
Capture mode:
Unused.
Compare mode:
Unused.
PWM mode:
These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPR1L.

bit 3-0 **CCP1M<3:0>:** ECCP Mode Select bits
0000 = Capture/Compare/PWM off (resets ECCP module)
0001 = Unused (reserved)
0010 = Compare mode, toggle output on match (CCP1IF bit is set)
0011 = Unused (reserved)
0100 = Capture mode, every falling edge
0101 = Capture mode, every rising edge
0110 = Capture mode, every 4th rising edge
0111 = Capture mode, every 16th rising edge
1000 = Compare mode, set output on match (CCP1IF bit is set)
1001 = Compare mode, clear output on match (CCP1IF bit is set)
1010 = Compare mode, generate software interrupt on match (CCP1IF bit is set, CCP1 pin is unaffected)
1011 = Compare mode, trigger special event (CCP1IF bit is set; CCP1 resets TMR1 and starts an A/D conversion, if the ADC module is enabled)
1100 = PWM mode; P1A, P1C active-high; P1B, P1D active-high
1101 = PWM mode; P1A, P1C active-high; P1B, P1D active-low
1110 = PWM mode; P1A, P1C active-low; P1B, P1D active-high
1111 = PWM mode; P1A, P1C active-low; P1B, P1D active-low

TABLE 10-2: SUMMARY OF REGISTERS ASSOCIATED WITH CAPTURE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
CCP1CON(1)	P1M1	P1M0	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	0000 0000	0000 0000
CCPR1L(1)	Capture/Compare/PWM Register 1 Low Byte								xxxx xxxx	uuuu uuuu
CCPR1H(1)	Capture/Compare/PWM Register 1 High Byte								xxxx xxxx	uuuu uuuu
INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	0000 0000
PIE1	—	ADIE(1)	CCP1IE(1)	C2IE	C1IE	—	TMR2IE(1)	TMR1IE	-000 0-00	0000 0-00
PIR1	—	ADIF(1)	CCP1IF(1)	C2IF	C1IF	—	TMR2IF(1)	TMR1IF	-000 0-00	0000 0-00
T1CON	T1GINV	TMR1GE	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	0000 0000	uuuu uuuu
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	--11 1111	--11 1111
TRISC	—	—	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	--11 1111	--11 1111

Legend: – = Unimplemented locations, read as '0', u = unchanged, x = unknown. Shaded cells are not used by the Capture, Compare and PWM.
Note 1: PIC16F616/16HV616 only.

10.4.3 START-UP CONSIDERATIONS

When any PWM mode is used, the application hardware must use the proper external pull-up and/or pull-down resistors on the PWM output pins.

Note:	When the microcontroller is released from Reset, all of the I/O pins are in the high-impedance state. The external circuits must keep the power switch devices in the OFF state until the microcontroller drives the I/O pins with the proper signal levels or activates the PWM output(s).

The CCP1M<1:0> bits of the CCP1CON register allow the user to choose whether the PWM output signals are active-high or active-low for each pair of PWM output pins (P1A/P1C and P1B/P1D). The PWM output polarities must be selected before the PWM pins are configured as outputs. Changing the polarity configuration while the PWM pins are configured as outputs is not recommended since it may result in damage to the application circuits.

The P1A, P1B, P1C and P1D output latches may not be in the proper states when the PWM module is initialized. Enabling the PWM pins for output at the same time as the Enhanced PWM modes may cause damage to the application circuit. The Enhanced PWM modes must be enabled in the proper Output mode and complete a full PWM cycle before configuring the PWM pins as outputs. The completion of a full PWM cycle is indicated by the TMR2IF bit of the PIR1 register being set as the second PWM period begins.

NOTES:

12.3.5 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows:

- PWRT time-out is invoked after POR has expired.
- OST is activated after the PWRT time-out has expired.

The total time-out will vary based on oscillator configuration and $\overline{\text{PWRTE}}$ bit status. For example, in EC mode with $\overline{\text{PWRTE}}$ bit erased (PWRT disabled), there will be no time-out at all. Figure 12-4, Figure 12-5 and Figure 12-6 depict time-out sequences.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then, bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 12-5). This is useful for testing purposes or to synchronize more than one PIC16F610/616/16HV610/616 device operating in parallel.

Table 12-5 shows the Reset conditions for some special registers, while Table 12-4 shows the Reset conditions for all the registers.

12.3.6 POWER CONTROL (PCON) REGISTER

The Power Control register PCON (address 8Eh) has two Status bits to indicate what type of Reset occurred last.

Bit 0 is $\overline{\text{BOR}}$ (Brown-out). $\overline{\text{BOR}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent Resets to see if $\overline{\text{BOR}}$ = 0, indicating that a Brown-out has occurred. The $\overline{\text{BOR}}$ Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (BOREN<1:0> = 00 in the Configuration Word register).

Bit 1 is $\overline{\text{POR}}$ (Power-on Reset). It is a '0' on Power-on Reset and unaffected otherwise. The user must write a '1' to this bit following a Power-on Reset. On a subsequent Reset, if $\overline{\text{POR}}$ is '0', it will indicate that a Power-on Reset has occurred (i.e., V_{DD} may have gone too low).

For more information, see **Section 12.3.4 "Brown-out Reset (BOR)"**.

TABLE 12-1: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out Reset		Wake-up from Sleep
	$\overline{\text{PWRTE}}$ = 0	$\overline{\text{PWRTE}}$ = 1	$\overline{\text{PWRTE}}$ = 0	$\overline{\text{PWRTE}}$ = 1	
XT, HS, LP	T_{PWRT} + 1024 • T_{OSC}	1024 • T_{OSC}	T_{PWRT} + 1024 • T_{OSC}	1024 • T_{OSC}	1024 • T_{OSC}
RC, EC, INTOSC	T_{PWRT}	—	T_{PWRT}	—	—

TABLE 12-2: STATUS/PCON BITS AND THEIR SIGNIFICANCE

$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Condition
0	x	1	1	Power-on Reset
u	0	1	1	Brown-out Reset
u	u	0	u	WDT Reset
u	u	0	0	WDT Wake-up
u	u	u	u	$\overline{\text{MCLR}}$ Reset during normal operation
u	u	1	0	$\overline{\text{MCLR}}$ Reset during Sleep

Legend: u = unchanged, x = unknown

TABLE 12-3: SUMMARY OF REGISTERS ASSOCIATED WITH BROWN-OUT RESET

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets(1)
PCON	—	—	—	—	—	—	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	---- --qq	---- --uu
STATUS	IRP	RP1	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	0001 1xxx	000q quuu

Legend: u = unchanged, x = unknown, – = unimplemented bit, reads as '0', q = value depends on condition. Shaded cells are not used by BOR.

Note 1: Other (non Power-up) Resets include $\overline{\text{MCLR}}$ Reset and Watchdog Timer Reset during normal operation.

12.5 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (e.g., W and STATUS registers). This must be implemented in software.

Temporary holding registers W_TEMP and STATUS_TEMP should be placed in the last 16 bytes of GPR (see Figure 2-4). These 16 locations are common to all banks and do not require banking. This makes context save and restore operations simpler. The code shown in Example 12-1 can be used to:

- Store the W register
- Store the STATUS register
- Execute the ISR code
- Restore the Status (and Bank Select Bit register)
- Restore the W register

Note:	The PIC16F610/616/16HV610/616 does not require saving the PCLATH. However, if computed GOTO's are used in both the ISR and the main code, the PCLATH must be saved and restored in the ISR.

EXAMPLE 12-1: SAVING STATUS AND W REGISTERS IN RAM

```
MOVWF   W_TEMP              ;Copy W to TEMP register
SWAPF   STATUS,W            ;Swap status to be saved into W
                            ;Swaps are used because they do not affect the status bits
MOVWF   STATUS_TEMP         ;Save status to bank zero STATUS_TEMP register
:
:(ISR)                      ;Insert user code here
:
SWAPF   STATUS_TEMP,W       ;Swap STATUS_TEMP register into W
                            ;(sets bank to original state)
MOVWF   STATUS              ;Move W into STATUS register
SWAPF   W_TEMP,F            ;Swap W_TEMP
SWAPF   W_TEMP,W            ;Swap W_TEMP into W
```

12.10 In-Circuit Serial Programming™

The PIC16F610/616/16HV610/616 microcontrollers can be serially programmed while in the end application circuit. This is simply done with five connections for:

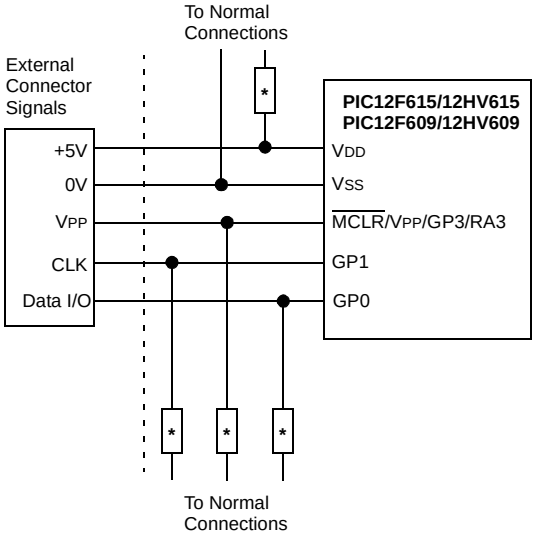
- clock
- data
- power
- ground
- programming voltage

This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a Program/Verify mode by holding the RA0 and RA1 pins low, while raising the MCLR (V_{PP}) pin from V_{IL} to V_{IHH}. See the *Memory Programming Specification* (DS41284) for more information. RA0 becomes the programming data and RA1 becomes the programming clock. Both RA0 and RA1 are Schmitt Trigger inputs in Program/Verify mode.

A typical In-Circuit Serial Programming connection is shown in Figure 12-10.

FIGURE 12-10: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING™ CONNECTION



* Isolation devices (as required)

Note:	To erase the device V_{DD} must be above the Bulk Erase V_{DD} minimum given in the *Memory Programming Specification* (DS41284)

12.11 In-Circuit Debugger

Since in-circuit debugging requires access to three pins, MPLAB® ICD 2 development with an 14-pin device is not practical. A special 28-pin PIC16F610/616/16HV610/616 ICD device is used with MPLAB ICD 2 to provide separate clock, data and MCLR pins and frees all normally available pins to the user.

A special debugging adapter allows the ICD device to be used in place of a PIC16F610/616/16HV610/616 device. The debugging adapter is the only source of the ICD device.

When the ICD pin on the PIC16F610/616/16HV610/616 ICD device is held low, the In-Circuit Debugger functionality is enabled. This function allows simple debugging functions when used with MPLAB ICD 2. When the microcontroller has this feature enabled, some of the resources are not available for general use. Table 12-9 shows which features are consumed by the background debugger.

TABLE 12-9: DEBUGGER RESOURCES

Resource	Description
I/O pins	ICDCLK, ICDDATA
Stack	1 level
Program Memory	Address 0h must be NOP 700h-7FFh

For more information, see "*MPLAB® ICD 2 In-Circuit Debugger User's Guide*" (DS51331), available on Microchip's web site (www.microchip.com).

15.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40° to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +6.5V
Voltage on $\overline{MCLR}$ with respect to Vss ..... -0.3V to +13.5V
Voltage on all other pins with respect to V_{SS} ..... -0.3V to (V_{DD} + 0.3V)
Total power dissipation(1) ..... 800 mW
Maximum current out of V_{SS} pin ..... 95 mA
Maximum current into V_{DD} pin ..... 95 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ± 20 mA
Output clamp current, I_{OK} (Vo < 0 or Vo >V_{DD}) ..... ± 20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by PORTA and PORTC (combined) ..... 90 mA
Maximum current sourced PORTA and PORTC (combined) ..... 90 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(Vol \times I_{OL})$.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

TABLE 15-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
30	TMCL	$\overline{\text{MCLR}}$ Pulse Width (low)	2 5	— —	— —	µs µs	VDD = 5V, -40°C to +85°C VDD = 5V, -40°C to +125°C
31*	TWDT	Watchdog Timer Time-out Period (No Prescaler)	10 10	20 20	30 35	ms ms	VDD = 5V, -40°C to +85°C VDD = 5V, -40°C to +125°C
32	TOST	Oscillation Start-up Timer Period**(1, 2)**	—	1024	—	TOSC	**(NOTE 3)**
33*	TPWRT	Power-up Timer Period	40	65	140	ms	
34*	TIOZ	I/O High-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	2.0	µs	
35*	VBOR	Brown-out Reset Voltage	2.0	2.15	2.3	V	**(NOTE 4)**
36*	VHYST	Brown-out Reset Hysteresis	—	100	—	mV	
37*	TBOR	Brown-out Reset Minimum Detection Period	100	—	—	µs	VDD ≤ VBOR

Legend: TBD = To Be Determined

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

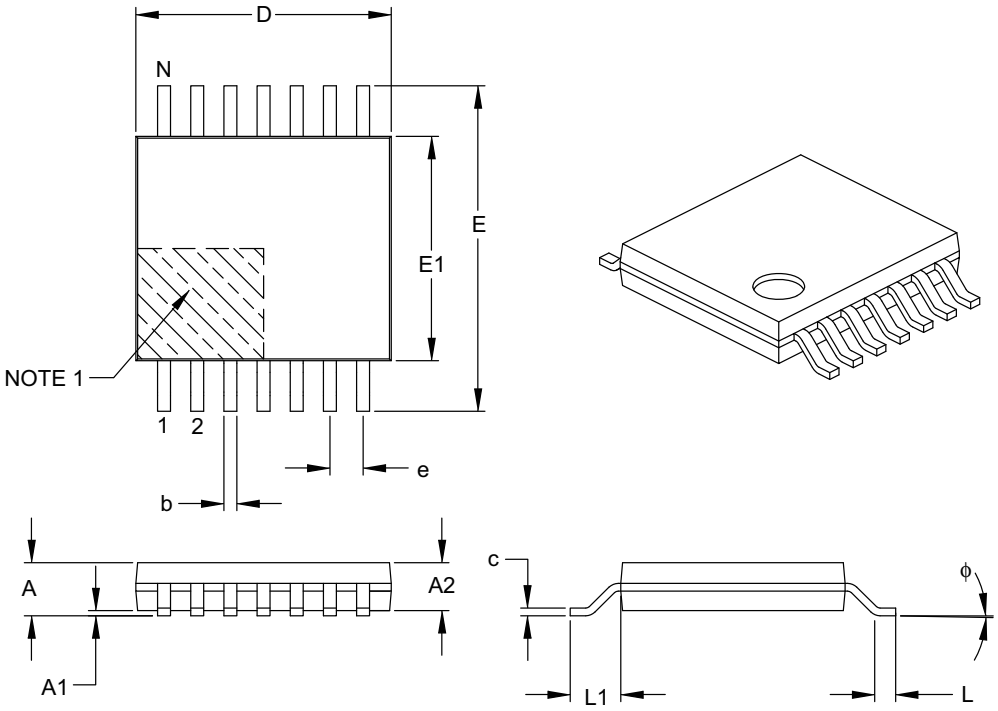
2: By design.

3: Period of the slower clock.

4: To ensure these voltage tolerances, VDD and VSS must be capacitivey decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

14-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	–	0.15
Overall Width	E		6.40 BSC	
Molded Package Width	E1	4.30	4.40	4.50
Molded Package Length	D	4.90	5.00	5.10
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	–	8°
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.19	–	0.30

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

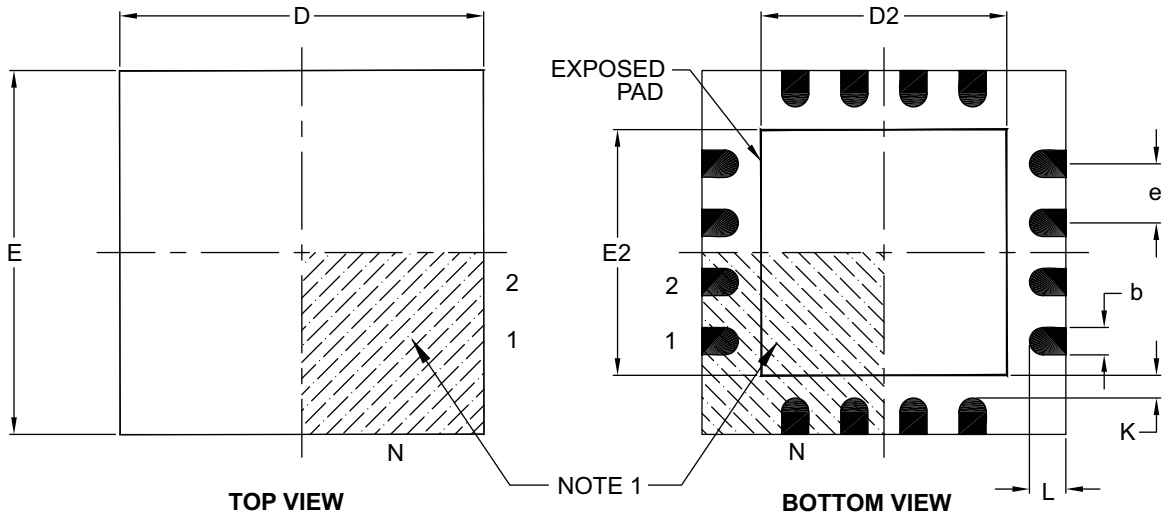
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

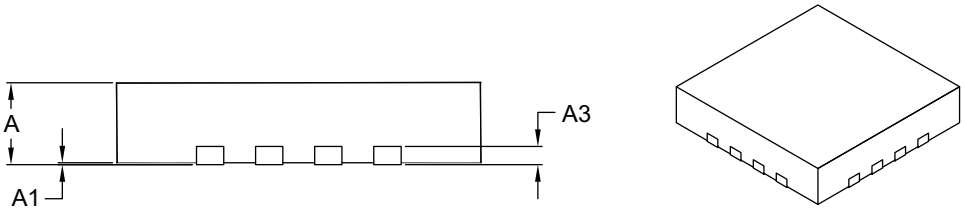
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-087B

16-Lead Plastic Quad Flat, No Lead Package (ML) – 4x4x0.9 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		16	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.50	2.65	2.80
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.50	2.65	2.80
Contact Width	b	0.25	0.30	0.35
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

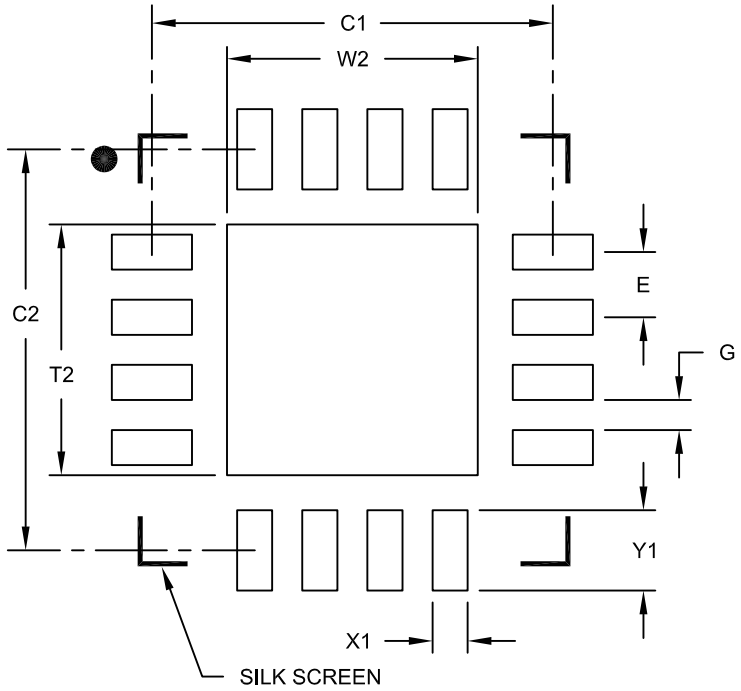
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-127B

16-Lead Plastic Quad Flat, No Lead Package (ML) - 4x4x0.9mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			2.50
Optional Center Pad Length	T2			2.50
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Width (X28)	X1			0.35
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.30		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2127A

APPENDIX B: MIGRATING FROM OTHER PIC® DEVICES

This discusses some of the issues in migrating from other PIC® devices to the PIC16F6XX Family of devices.

B.1 PIC16F676 to PIC16F610/616/16HV610/616

TABLE B-1: FEATURE COMPARISON

Feature	PIC16F676	PIC16F610/16HV610	PIC16F616/16HV616
Max Operating Speed	20 MHz	20 MHz	20 MHz
Max Program Memory (Words)	1024	1024	2048
SRAM (bytes)	64	64	128
A/D Resolution	10-bit	None	10-bit
Timers (8/16-bit)	1/1	1/1	2/1
Oscillator Modes	8	8	8
Brown-out Reset	Y	Y	Y
Internal Pull-ups	RA0/1/2/4/5	RA0/1/2/4/5, $\overline{\text{MCLR}}$	RA0/1/2/4/5, $\overline{\text{MCLR}}$
Interrupt-on-change	RA0/1/2/3/4/5	RA0/1/2/3/4/5	RA0/1/2/3/4/5
Comparator	1	2	2
ECCP	N	N	Y
INTOSC Frequencies	4 MHz	4/8 MHz	4/8 MHz
Internal Shunt Regulator	N	Y (PIC16HV610)	Y (PIC16HV616)

Note: This device has been designed to perform to the parameters of its data sheet. It has been tested to an electrical specification designed to determine its conformance with these parameters. Due to process differences in the manufacture of this device, this device may have different performance characteristics than its earlier version. These differences may cause this device to perform differently in your application than the earlier version of this device.